

INTERCONNECT STRUCTURE AND METHOD OF MAKING SAME

ABSTRACT OF THE DISCLOSURE

5 An interconnect structure having an increased chip
connector pad and plated through hole density is provided. In
particular, the interconnect structure includes a substrate
having at least one plated through hole therein, and a first
conductive layer sealing the at least one plated through hole.
The substrate includes a layer of dielectric material thereon.
The dielectric layer includes at least one aperture selectively
positioned directly over the at least one plated through hole.
The substrate further includes a metal layer, at least a pair
of conductive layers that can carry signals, and at least
another pair of conductive layers that can carry power, wherein
the pair of conductive layers are shielded by the metal layer
and the other pair of conductive layers.